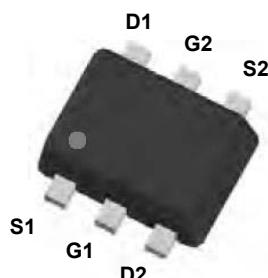
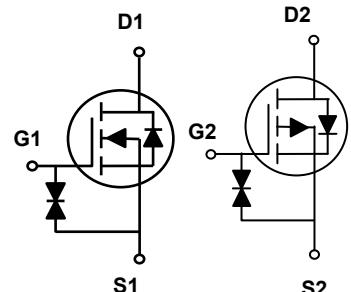


Main Product Characteristics

$V_{(BR)DSS}$	20V	-20V
$R_{DS(ON)}$	300mΩ	600mΩ
I_D	800mA	-400mA



SOT-563



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for notebook, load switch, networking and hand-held devices
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSF2120Y utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value		Unit
Drain-Source Voltage	V_{DS}	20	-20	V
Gate-Source Voltage	V_{GS}	± 8	± 8	V
Drain Current – Continuous ($T_C=25^\circ\text{C}$)	I_D	800	-400	mA
Drain Current – Continuous ($T_C=100^\circ\text{C}$)		510	-250	mA
Drain Current – Pulsed ¹	I_{DM}	3.2	-1.6	A
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	312	312	mW
Power Dissipation – Derate above 25°C	P_D	2.5	2.5	$\text{mW}/^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to +150	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	400	$^\circ\text{C}/\text{W}$

N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_D=1\text{mA}$	---	-0.01	---	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current		$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
	I_{DS}	$V_{\text{DS}}=16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
Gate-Source Leakage Current		$V_{\text{GS}}=\pm 6\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 20	μA
On Characteristics						
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=4.5\text{V}$, $I_D=0.5\text{A}$	---	200	300	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$, $I_D=0.4\text{A}$	---	235	400	
		$V_{\text{GS}}=1.8\text{V}$, $I_D=0.2\text{A}$	---	295	550	
		$V_{\text{GS}}=1.5\text{V}$, $I_D=0.1\text{A}$	---	365	800	
		$V_{\text{GS}}=1.2\text{V}$, $I_D=0.1\text{A}$	---	600	1500	
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	0.3	0.6	1.0	V
$V_{\text{GS(th)}}/\text{Temperature Coefficient}$	$\Delta V_{\text{GS(th)}}$		---	3	---	$\text{mV}/^\circ\text{C}$
Dynamic and Switching Characteristics						
Total Gate Charge ^{2, 3}	Q_g	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=0.5\text{A}$	---	1	2	nC
Gate-Source Charge ^{2, 3}	Q_{gs}		---	0.26	0.5	
Gate-Drain Charge ^{2, 3}	Q_{gd}		---	0.2	0.4	
Turn-On Delay Time ^{2, 3}	$T_{\text{d(on)}}$	$V_{\text{DD}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $R_G=10\Omega$, $I_D=0.5\text{A}$	---	5	10	nS
Rise Time ^{2, 3}	T_r		---	3.5	7	
Turn-Off Delay Time ^{2, 3}	$T_{\text{d(off)}}$		---	14	28	
Fall Time ^{2, 3}	T_f		---	6	12	
Input Capacitance	C_{iss}	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	38.2	75	pF
Output Capacitance	C_{oss}		---	14.4	28	
Reverse Transfer Capacitance	C_{rss}		---	6	12	
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_G=V_D=0\text{V}$, Force Current	---	---	0.8	A
Pulsed Source Current	I_{SM}		---	---	1.6	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_s=0.2\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$	-20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$		Reference to 25°C , $I_D=-1\text{mA}$	---	-0.01	---	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{DS}}=-16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	-10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 8\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 20	μA
On Characteristics						
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-4.5\text{V}$, $I_D=-0.3\text{A}$	---	440	600	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$, $I_D=-0.2\text{A}$	---	610	850	
		$V_{\text{GS}}=-1.8\text{V}$, $I_D=-0.1\text{A}$	---	810	1200	
		$V_{\text{GS}}=-1.5\text{V}$, $I_D=-0.1\text{A}$	---	1020	1600	
		$V_{\text{GS}}=-1.2\text{V}$, $I_D=-0.1\text{A}$	---	1800	3000	
Gate Threshold Voltage	$V_{\text{GS(th)}}$		-0.3	-0.6	-1.0	V
$\Delta V_{\text{GS(th)}}$		$V_{\text{GS}}=V_{\text{DS}}$, $I_D=-250\mu\text{A}$	---	3	---	$\text{mV}/^\circ\text{C}$
Dynamic and Switching Characteristics						
Total Gate Charge ^{2, 3}	Q_g	$V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_D=-0.2\text{A}$	---	1	2	nC
Gate-Source Charge ^{2, 3}	Q_{gs}		---	0.28	0.5	
Gate-Drain Charge ^{2, 3}	Q_{gd}		---	0.18	0.4	
Turn-On Delay Time ^{2, 3}	$T_{\text{d(on)}}$	$V_{\text{DD}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $R_G=10\Omega$, $I_D=-0.2\text{A}$	---	8	16	nS
Rise Time ^{2, 3}	T_r		---	5.2	10	
Turn-Off Delay Time ^{2, 3}	$T_{\text{d(off)}}$		---	30	60	
Fall Time ^{2, 3}	T_f		---	18	36	
Input Capacitance	C_{iss}		---	40	78	
Output Capacitance	C_{oss}	$V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	15	30	pF
Reverse Transfer Capacitance	C_{rss}		---	6.5	13	
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_G=V_D=0\text{V}$, Force Current	---	---	-0.4	A
Pulsed Source Current	I_{SM}		---	---	-0.8	A
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_s=-0.2\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

Notes:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

N-Channel Typical Electrical and Thermal Characteristic Curves

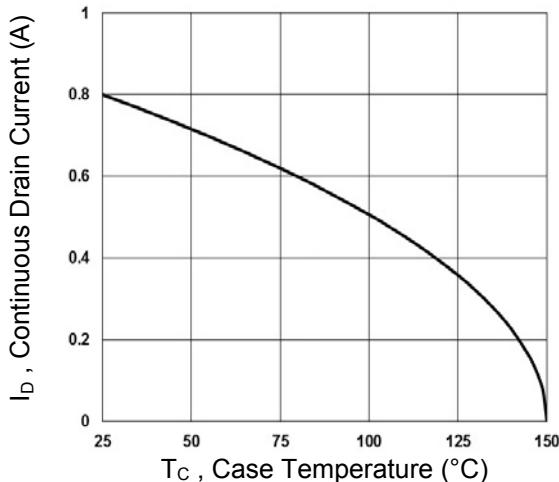


Fig.1 Continuous Drain Current vs. T_c

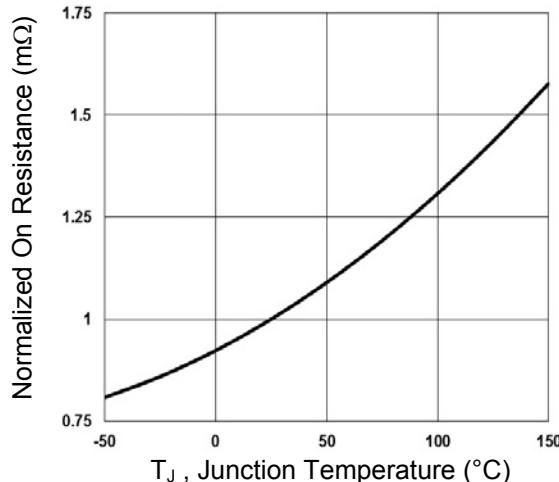


Fig.2 Normalized R_{DS(ON)} vs. T_J

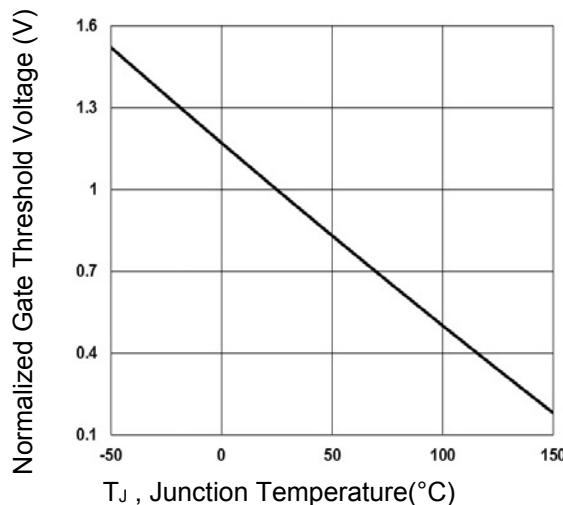


Fig.3 Normalized V_{th} vs. T_J

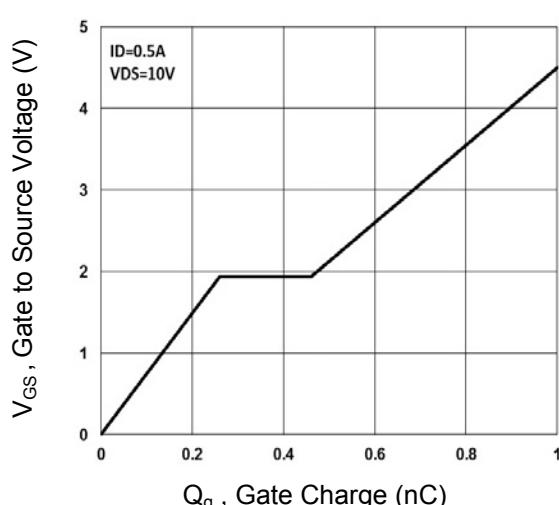


Fig.4 Gate Charge Waveform

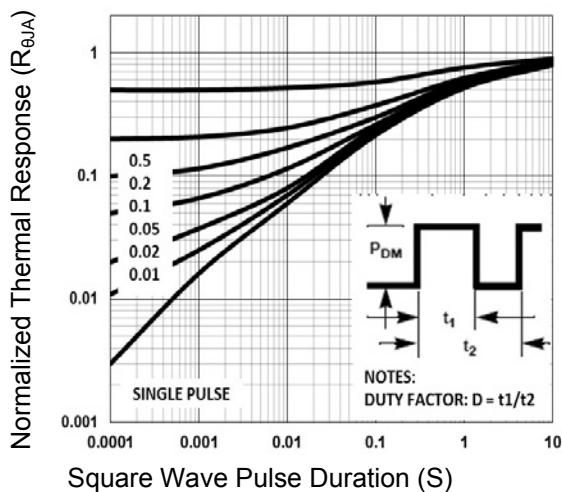


Fig.5 Normalized Transient Impedance

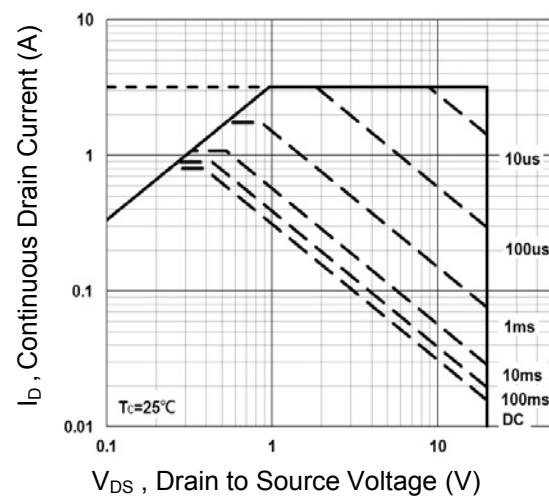


Fig.6 Maximum Safe Operation Area

N-Channel Typical Electrical and Thermal Characteristic Curves

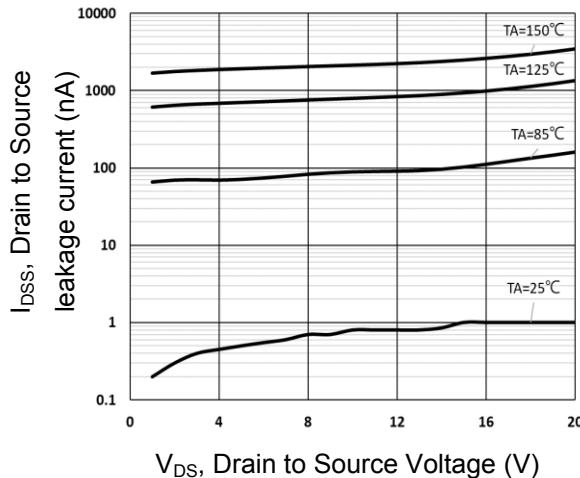


Fig.7 Leakage Current vs. V_{DS}

P-Channel Typical Electrical and Thermal Characteristic Curves

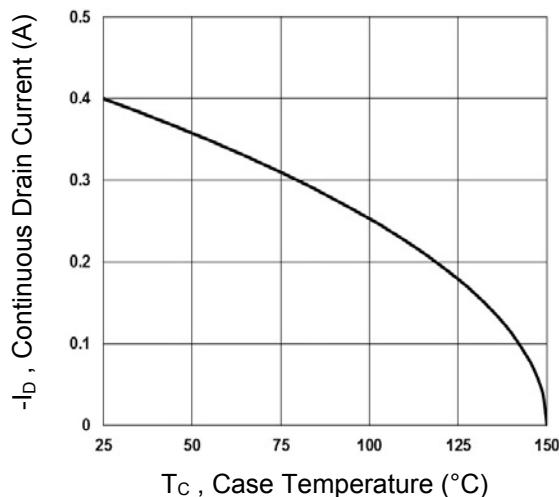


Fig.8 Continuous Drain Current vs. T_C

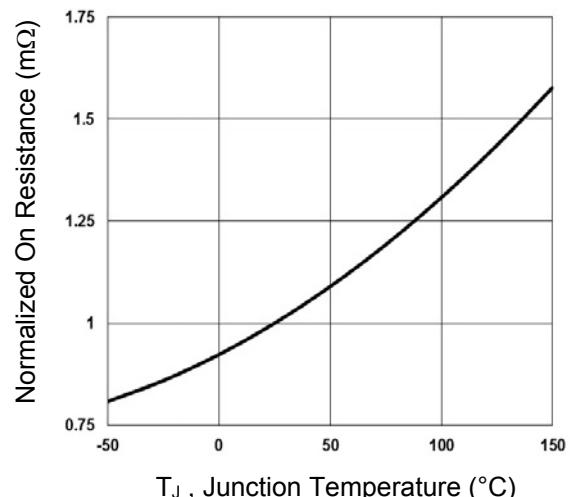
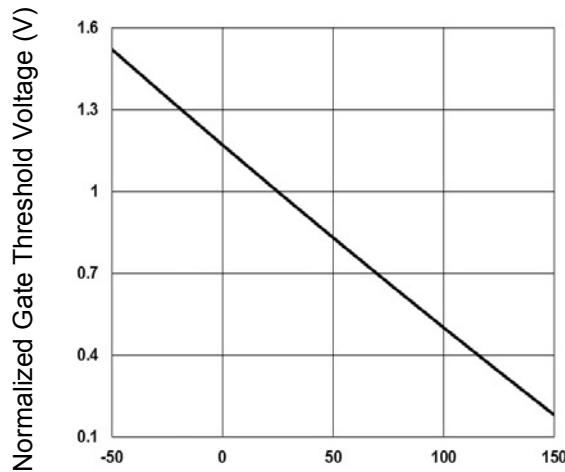


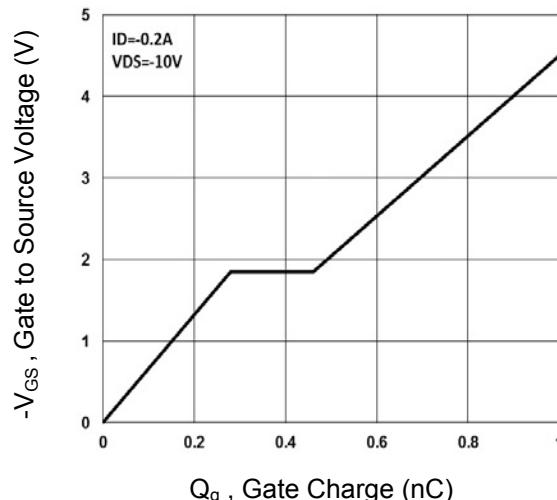
Fig.9 Normalized $R_{DS(ON)}$ vs. T_J

P-Channel Typical Electrical and Thermal Characteristic Curves



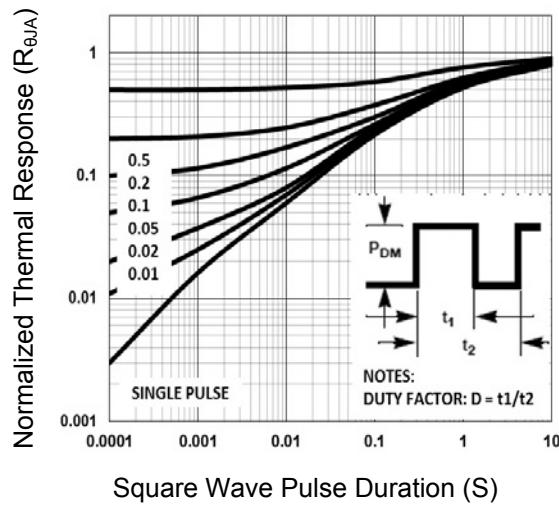
T_J , Junction Temperature(°C)

Fig.10 Normalized V_{th} vs T_J



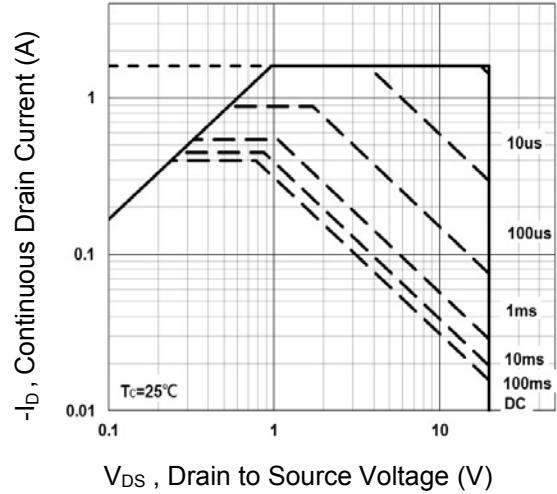
$-V_{GS}$, Gate to Source Voltage (V)

Fig.11 Gate Charge Waveform



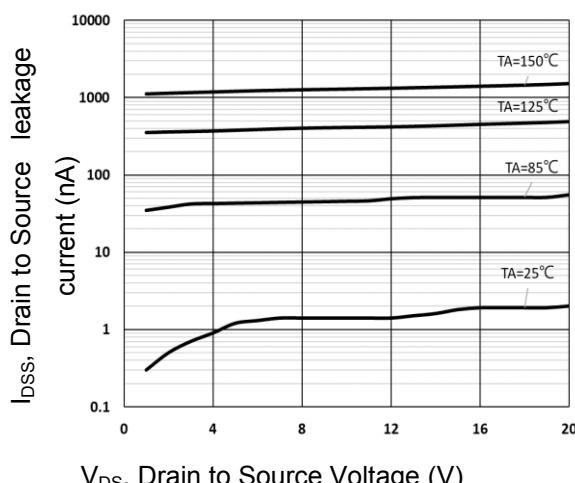
Square Wave Pulse Duration (S)

Fig.12 Normalized Transient Impedance



$-V_{DS}$, Drain to Source Voltage (V)

Fig.13 Maximum Safe Operation Area

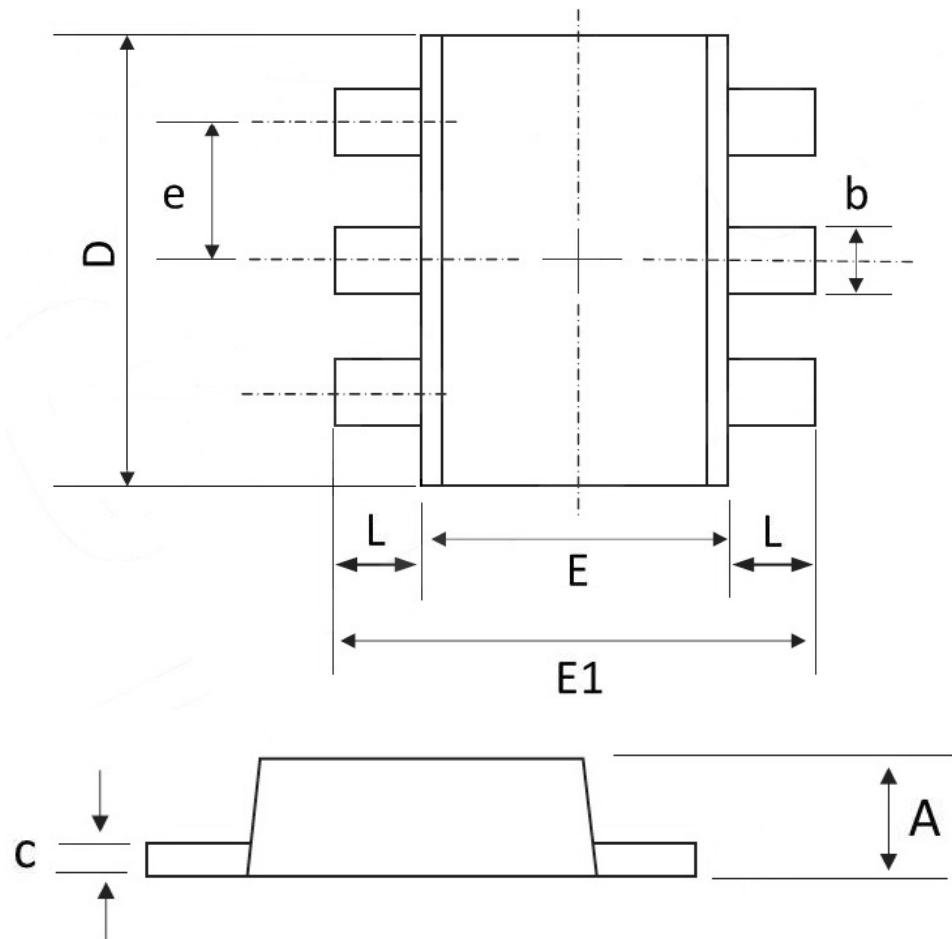


V_{DS} , Drain to Source Voltage (V)

Fig.14 Leakage Current vs. V_{DS}

Package Outline Dimensions

SOT-563



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.600	0.500	0.024	0.020
b	0.300	0.150	0.012	0.006
c	0.180	0.100	0.007	0.004
D	1.700	1.500	0.067	0.059
E	1.250	1.100	0.049	0.043
E1	1.700	1.550	0.067	0.061
e	0.5BSC		0.02BSC	
L	0.300	0.100	0.012	0.004